



Product Information

www.miller-stephenson.com

MS-917 Thermoset Epoxy

Description:

MS-917 is a two component, thixotropic, room temperature curing epoxy adhesive. It's specially formulated where a limited amount of flow is desirable. It is ideal for bonding most materials, such as metal, glass, ceramics, plastics, wood and rubber. The thixotropic nature of the adhesive will hold parts in place without special fixtures while the hardening process is taking place. Versatility in curing options between 74°F/23°C and 212°F/100°C.

Advantages:

- 24 hour cure at room temperature
- 1:1 ratio mix ratio (by weight or volume)
- Good adhesion to wide variety of surfaces
- Packaged in cartridge form for ease of mixing

Ratio & Cure:

Part A (Resin) Tan, Part B (Hardener) Tan

Mixed: Tan

Mix Ratio: 1:1 by weight

Pot Life: 1 Hour at 74°F/23°C

Recommended cure: 176°F/80°C for 2 Hours

Minimum Alternative Cure(s):

May not achieve performance properties listed below

212°F/100°C for 30 Minutes

74°F/23°C for 24 hours

Physical Properties¹

Viscosity (74°F/23°C) @ 2.5 rpm:	80,000-120,000 cPs
Thixotropic Index:	2.1
Glass Transition Temp:	≥ 55°C (Dynamic Cure: 20-200°C/ISO 25 min; Ramp-10-200°C @ 20°C//Min)
Coefficient of Thermal Expansion (CTE)	
Below Tg:	66 x 10 ⁻⁶ in/in°C
Above Tg:	248 x 10 ⁻⁶ in/in°C
Shore D Hardness:	64
Lap Shear @ 23C:	> 2,000 psi
Die Shear @ 23C:	≥ 10 Kg 3,556 psi
Degradation Temp:	687°F/364°C
Weight Loss:	
@ 200°C:	1.4 %
@ 250°C:	2.2 %
@ 300°C:	4.16%
Suggested Operating Temperature:	< 250°C (Intermittent)
Storage Modulus:	123,527 psi
Particle Size:	≤ 20 microns

For technical information call 800.992.2424 or 203.743.4447
For product sales: CT 800.442.3424, CA 800.771.8161, IL 800.447.4866, Canada 800.307.2199
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Electrical and Thermal Properties¹

Thermal Conductivity.....	NA
Volume Resistivity @ 23°C.....	$\geq 3 \times 10^{13}$ Ohm-cm
Dielectric Constant (1KHz):.....	3.17
Dissipation Factor (1KHz).....	0.021

Directions

1. Clean surfaces to be bonded. Both surfaces must be clean, dry and free of oil, grease or wax. Roughen nonporous surfaces with sandpaper or emery paper for hard materials.
2. The paste-like appearance allows it to be spread by hand using a spatula or blade.
3. Cover entire area.
4. Join parts together firmly. Squeeze out excess adhesive to form a thin glue line. A larger area will require more pressure.
5. Remove excess adhesive promptly before adhesive hardens. Scrape with a putty knife.

Clean Up

Always wear appropriate protective equipment such as safety glasses and gloves. Clean uncured material with a mild solvent. Cured materials can only be removed mechanically.

Safety Data Sheet (SDS) is available upon request.

¹Cure condition: 80°C for 2 hours. Different batches, conditions & application yield differing results. The data is not guaranteed. To be used as a guide only, not as a specification.

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